

AMENDMENTS

In the Claims:

1. (Currently Amended) A curable composition that forms a continuous phase and a dispersoid at ambient temperatures, wherein
the continuous phase is a liquid at ~~normal~~ ambient temperatures and comprises (a) a compound having two or more epoxy groups in a molecule, and
the dispersoid comprises (b) a compound present as solid particles in a continuous phase at ~~normal~~ ambient temperatures and having two or more amino groups in a molecule.
2. (Original) The curable composition of claim 1, wherein the compound having two or more amino groups in a molecule is an aromatic amine compound having a benzoxazole structure.
3. (Currently Amended) The curable composition of claim 1 ~~or 2~~, wherein the compound having two or more epoxy groups in a molecule is a liquid at ambient temperatures.
4. (Currently Amended) The curable composition of ~~any of claims claim 1 to 3~~, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.
5. (Currently Amended) The curable composition of ~~any of claims claim 1 to 3~~, wherein the solid particles have a volume average particle size of 0.05 – 50 µm.
6. (New) The curable composition of claim 1 ~~or 2~~, wherein the compound having two or more epoxy groups in a molecule is a liquid at ambient temperatures.

7. (New) The curable composition of claim 2, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.

8. (New) The curable composition of claim 3, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.

9. (New) The curable composition of claim 6, wherein the continuous phase contains an organic solvent having a boiling point of not higher than 200°C.

10. (New) The curable composition of claim 2, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

11. (New) The curable composition of claim 3, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

12. (New) The curable composition of claim 6, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

13. (New) The curable composition of claim 4, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

14. (New) The curable composition of claim 7, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

15. (New) The curable composition of claim 8, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .

16. (New) The curable composition of claim 9, wherein the solid particles have a volume average particle size of 0.05 - 50 μm .